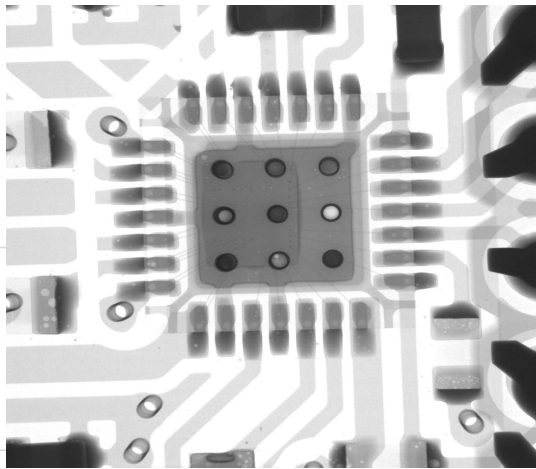


LEX Lite

The first option for X-ray inspection of microelectronics and electromechanical goods is the LEX Lite, a compact, accurate micro-focus X-ray inspection device that is ideal for R&D facilities, labs, quality inspection rooms, and other settings.

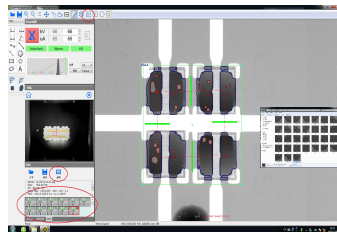
Equipment Parameters

Dimension	L850mm×W1000mm×H1700mm
Input Power	220V 10A/110V 15A 50-60HZ
Max Sample Size	280mm×320mm
OS	IPC WIN7/ WIN10 64 bit
N.W.	About 750KG



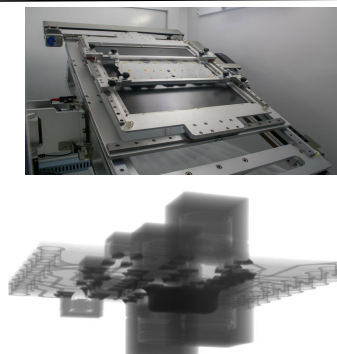
CNC Automatic Inspection

•CNC automated inspection:
Depending on the user's settings, the LEX family may do CNC inspection. Reports and images are automatically created.



Tilt photo/rotate photo function

•Tilt inspection feature: The LEX series offers a 360° rotating camera with no blind areas and support for multi-angle fault examination.



Advantages

- Small and simple to set up and use.
- Appropriate for BGA/CSP, Wafer, SOP/QFN, SMT and PTU packaging.
- High-resolution design yields a picture of superior quality.
- Quick location infrared auto-navigation and placement.
- CNC multi point array automated inspection mode.
- Easy-to-use software interface, little training expenses.
- Long lifespan: producing favorable COO and ROI.

X-ray Tube Spec

X-ray TubeType	Reflective sealed micro-focus ray source
Tube Voltage	40-90KV
Tube Current	10-200 μA
Max Output Power	8 W
Micro Focus Size	15μm

FPD Spec

Detector Type	Amorphous silicon flat panel detector
Pixel Matrix	1536×1536
FOV	130mm×130mm
Resolution	5.8Lp/mm
Image frame rate (1×1)	20fps
AD conversion digits	16bit

Dimensions

